

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Takayuki Dohi	09/03/2007
Shinji Nakahara	09/03/2007
Masaya Sakurai	09/03/2007
Masato Sakai	09/03/2007
RECEIVING PARTY DATA	
Name:	Sumco Corporation
Street Address:	2-1, Shibaura 1-chome, Minato-ku
City:	Tokyo
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13164511
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Total Attachments: 3	
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ASSIGNMENT

WHEREAS, I/WE, (1) Takayuki DOHI; (2) Shinji NAKAHARA; (3) Masaya SAKURAI; and (4) Masato SAKAI

Of (1) to (4) c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan

respectively, have invented certain improvements in
EPITAXIAL SILICON WAFER AND FABRICATION METHOD THEREOF

, for which we have executed an application for Letters Patent of the United States on the date we executed this Assignment as hereinafter set forth.

WHEREAS, SUMCO CORPORATION, a Japanese corporation, having its principal place of business in Tokyo, Japan, is desirous of acquiring an interest therein:

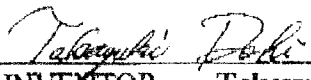
NOW, THEREFORE, for other good and valuable consideration, we the said (1) Takayuki DOHI; (2) Shinji NAKAHARA; (3) Masaya SAKURAI; and (4) Masato SAKAI, have sold, assigned, and transferred, and by these presents do sell, assign, and transfer unto the said SUMCO CORPORATION, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof.

We hereby authorize and request the Patent Office officials in the United States and any and all foreign countries to issue any and all of said Letters Patent, when

granted, to the said **SUMCO CORPORATION**, as the assignee of our entire right, title and interest in and to the same, for the sole use of the said **SUMCO CORPORATION**, its successors and assigns.

Further, we agree that we will communicate to the said **SUMCO CORPORATION**, or its representatives any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to the said **SUMCO CORPORATION**, make all rightful oaths and generally do everything possible to aid the said **SUMCO CORPORATION**, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, I have hereunto set my hand this 3rd day of September, 2007.



FIRST INVENTOR Takayuki DOHI

Witness:

(Name)

(Address)

(City, Country)

Shinji Nakahara
SECOND INVENTOR **SHINJI NAKAHARA**

Witness:

(Name)

(Address)

(City, Country)

Masaya Sakurai
THIRD INVENTOR **Masaya SAKURAI**

Witness:

(Name)

(Address)

(City, Country)

Masato Sakai
FOURTH INVENTOR **Masato SAKAI**

Witness:

(Name)

(Address)

(City, Country)